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Field Device Integration (FDI) - Part 103-4: Profiles - PROFINET

Táto norma obsahuje anglickú verziu európskej normy.  
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 11/15

Obsahuje: EN 62769-103-4:2015, IEC 62769-103-4:2015

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**Field Device Integration (FDI) - Part 103-4: Profiles - PROFINET  
(IEC 62769-103-4:2015)**

Intégration des appareils de terrain (FDI) - Partie 103-4:  
Profils - PROFINET  
(IEC 62769-103-4:2015)

Feldgeräteintegration (FDI) - Profile - Teil 103-4:  
PROFINET  
(IEC 62769-103-4:2015)

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## European foreword

The text of document 65E/355/CDV, future edition 1 of IEC 62769-103-4, prepared by SC 65E "Devices and integration in enterprise systems", of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62769-103-4:2015.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2016-03-16
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2018-06-16

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IEC 61158	NOTE	Harmonized in EN 61158 series.
IEC 61784-1	NOTE	Harmonized as EN 61784-1.
IEC 61804-4	NOTE	Harmonized as EN 61804-4 <sup>1)</sup> (not modified).

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1) To be published.

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61158-5-10	-	Industrial communication networks - Fieldbus specifications - Part 5-10: Application layer service definition - Type 10 elements	EN 61158-5-10	-
IEC 61784-2	-	Industrial communication networks - Profiles - Part 2: Additional fieldbus profiles for real- time networks based on ISO/IEC 8802-3	EN 61784-2	-
IEC 61804	series	Function blocks (FB) for process control - Electronic device description language (EDDL)	EN 61804	series
IEC 62541-100	2015	OPC unified architecture - Part 100: Device Interface	EN 62541-100	2015
IEC 62769-2	-	Field Device Integration (FDI) - Part 2: FDI Client	EN 62769-2 <sup>2)</sup>	-
IEC 62769-4	-	Field Device Integration (FDI) - Part 4: FDI Packages	EN 62769-4 <sup>2)</sup>	-
IEC 62769-5	-	Field Device Integration (FDI) - Part 5: FDI Information Model	EN 62769-5 <sup>2)</sup>	-
IEC 62769-6	-	Field Device Integration (FDI) - Part 6: FDI Technology Mapping	EN 62769-6 <sup>2)</sup>	-
IEC 62769-7	-	Field Device Integration (FDI) - Part 7: FDI Communication Devices	EN 62769-7 <sup>2)</sup>	-

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2) To be published.



# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



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**Field device integration (FDI) –  
Part 103-4: Profiles – PROFINET**

**Intégration des appareils de terrain (FDI) –  
Partie 103-4: Profils – PROFINET**





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# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



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**Field device integration (FDI) –  
Part 103-4: Profiles – PROFINET**

**Intégration des appareils de terrain (FDI) –  
Partie 103-4: Profils – PROFINET**

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**FIELD DEVICE INTEGRATION (FDI) –****Part 103-4: Profiles – PROFINET**

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International Standard IEC 62769-103-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

The text of this standard is based on the following documents:

CDV	Report on voting
65E/355/CDV	65E/418/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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- a) method for the supplying and installation of device-specific functionalities, see Patent Family DE10357276;
- b) method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
- d) extensible device object model, see Patent Family US12/893,680;

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## FIELD DEVICE INTEGRATION (FDI) –

### Part 103-4: Profiles – PROFINET

#### 1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-2\_CP 3/4, IEC 61784-2\_CP3/5 and IEC 61784-2\_CP3/6 (PROFINET<sup>1</sup>).

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158-5-10, *Industrial communication networks – Fieldbus specifications – Part 5-10: Application layer service definition – Type 10 elements*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC 8802-3*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC Unified Architecture – Part 100: OPC UA for Devices*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technically identical to FDI-2022.

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE 2 IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 3 IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

NOTE 4 IEC 62769-6 is technically identical to FDI-2026.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE 5 IEC 62769-7 is technically identical to FDI-2027.

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <[www.PROFIBUS.com](http://www.PROFIBUS.com)>

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PI Order No.: 2.352:2014, *GSDML Specification for PROFINET IO*; available at [www.PROFIBUS.com](http://www.PROFIBUS.com)

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